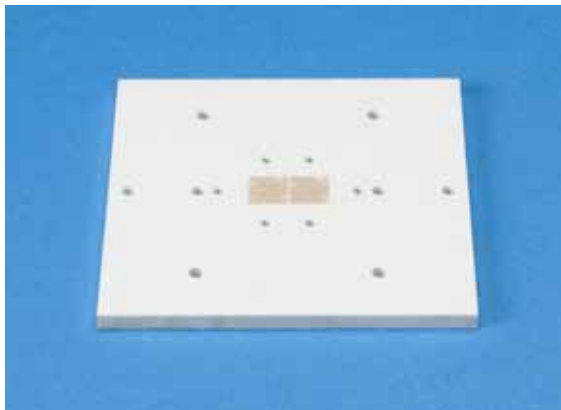


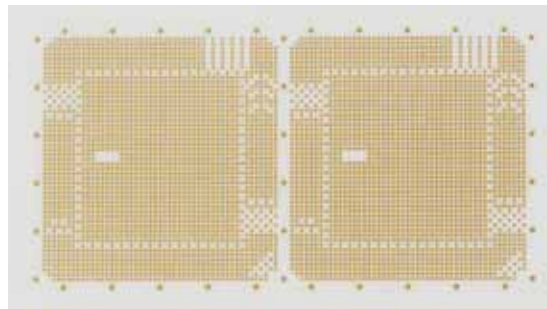
LTCC Interposer Substrate

LTCC Interposer Substrate



90x90x4.5mm

Enlarged DUT Pattern



Approx. 5,000 pads, 200μm pitch

Application

- Interposer substrates for semiconductor wafer test probe card.※

※LTCC Interposer Substrate

Thousands of bonding pads are densely packed onto an LSI semiconductor wafer. Testing of LSI semiconductor wafers cannot be performed without a probe card, because the fine-pitch bonding pads need to be expanded spatially by the probe card to be connectable to the tester. The LTCC interposer substrate is a key component of a probe card.

Features

- Low-resistance silver-paste lines and via holes are configured three-dimensionally on a multilayer substrate consisting of all LTCC layers. This permits the substrate to be compatible with area-array-type probe cards with fine pitch and ultra-high pin count. Thanks to the use of high frequency technologies, the substrate is also suitable for probe cards for testing high-frequency devices.

■Pogo pins Connected Type

